

METHODS OF FORMING SPIN ON GLASS LAYERS BY CURING REMAINING
PORTIONS THEREOF

ABSTRACT

Methods of forming a spin-on-glass (SOG) layer are disclosed. An SOG layer is formed on an integrated circuit substrate. A first curing process is performed on the SOG layer. Less than all of the SOG layer is removed from the integrated circuit substrate through a mask pattern on the SOG layer to provide a remaining portion of the SOG layer on the integrated circuit substrate. A second curing process is performed on the SOG layer. The remaining portion of the SOG layer is removed to expose the integrated circuit substrate.